COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

FAX: 886-2-2369 7233

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

CHIP STRUCTURE WITH BUMPS AND A PROCESS FOR FABRICATING THE SAME

the	specification of whic	h				
_X	is attached hereto.					
	was filed on					
	as Application Ser	ial No	and was amended on_		·	
appappappappappappappappappappapppappap	ecification, including t I acknowledge the plication in accordanc I hereby claim fore plication(s) for paten	the claims, as amended to duty to disclose informate with Title 37, Code or sign priority benefits under the or inventor's certificated;	nd understand the content I by any amendment referre mation which is material to f Federal Regulations, § 1. der Title 35, United States Co ate listed below and have ficate having a filing date be	ed to above. the patents 56(a). code, § 119 also identifi	ability of this of any foreigr ed below any	
	Number	Country	Date Filed(yyyy/mm/dd)	Yes	No	
	91100094	Taiwan, R.O.C.	2002/1/7	X		
tra))		ication and to	
	SEND CORRESPONDENCE TO:			DIRECT TELEPHONE CALLS TO: (Name and telephone number)		
	JIANQ CHYUN Intellectual Property Office 7F1, No. 100, Roosevelt Rd., Sec. 2, Taipei 100, Taiwan, R.O.C. TEL: 886-2-2369 2800		ïce Belind	la Lee		

COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Signature: 12 Chao-fu Weng Date: 30/2002

Sole or First Joint Inventor: Chao-Fu Weng

Citizenship: Taiwan, R.O.C.

Residence and Post Office Address: No. 19-3, Lane 19, Hsinchien Rd., Tainan, Taiwan, R.O.C.